

# The Exceptional Challenges of Exascale Computing

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# Agenda

- **Activities and investments in exascale**
- **Key challenges for achieving exascale**
- **Thoughts on the co-design process**
- **Working with the community**

# Activities and Investments

- **Intel Labs Europe**
  - Exascale Computing Research Center
  - ExaCluster Laboratory
  - ExaScience Lab
- **Universal Parallel Computing Research Center (UPCRC)**
  - *Client focus...*
- **Ubiquitous High Performance Computing (UHPC)**
- **Single-Chip Cloud Computer (SCC)**

# Investments - Intel Labs Europe

## Exascale Computing Research Center, Paris

- **Participants**
  - Intel
  - CEA
  - GENCI
  - Université de Versailles Saint-Quentin-en-Yvelines
- **Research Agenda**
  - Programming models
  - Performance optimization and analysis
  - Application tuning and optimization

# Investments - Intel Labs Europe

## ExaCluster Laboratory, Jülich

- **Participants**
  - Intel
  - Forschungszentrum Jülich
  - ParTec
- **Research Agenda**
  - System management
  - Software tools
  - Simulation

# Investments - Intel Labs Europe

## ExaScience Lab, Leuven

- **Participants**
  - Intel
  - Imec
  - U. Antwerp, Ghent U., Hasselt U., Katholieke U. Leuven, Vrije U. Brussel
- **Research Agenda**
  - Space weather application
  - Programming models
  - Power and reliability

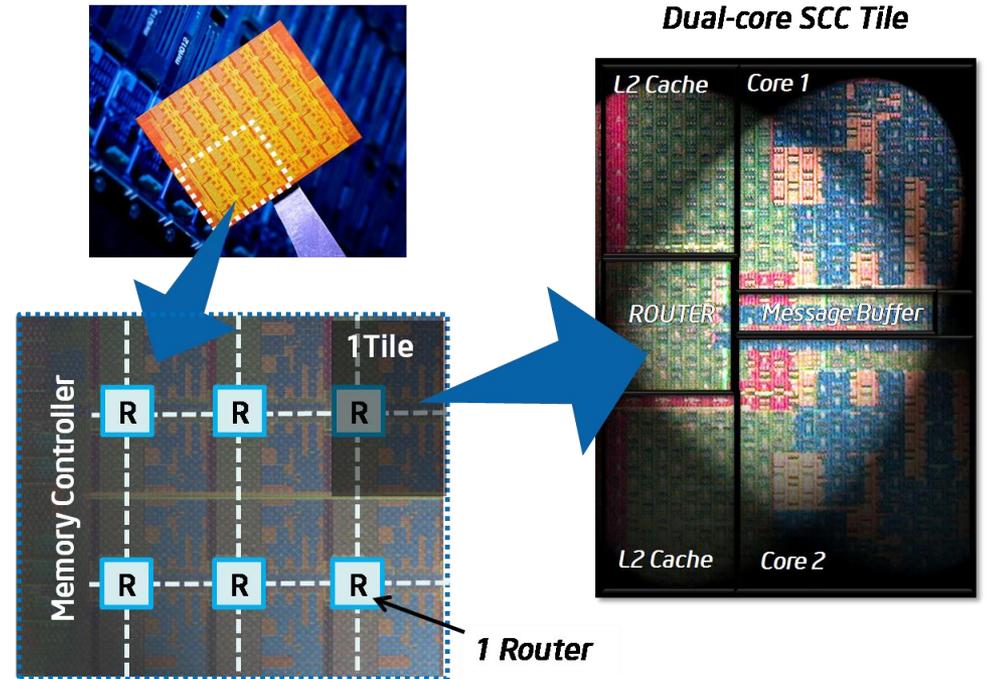
# Investments - UPCRC

## Universal Parallel Computing Research Center

- **Participants**
  - Intel
  - Microsoft
  - UCB
  - UIUC
- **Research Agenda (relevant subset)**
  - Deterministic languages
  - Scalable many core operations systems
  - Parallel correctness
  - Autotuners for linear algebra
  - Parallel patterns and frameworks

# Investments - SCC

- 24 dual-core tiles
- 6x4 mesh interconnect
- No cache-coherence between cores
- Message passing buffer
- Software-controlled frequency & voltage
- Choice of Linux or a few different research OSs.
- More than a cluster on a chip ... includes non-coherent memory



Technology	45nm Process
Interconnect	1 Poly, 9 Metal (Cu)
Transistors	Die: 1.3B, Tile: 48M
Tile Area	18.7mm <sup>2</sup>
Die Area	567.1mm <sup>2</sup>

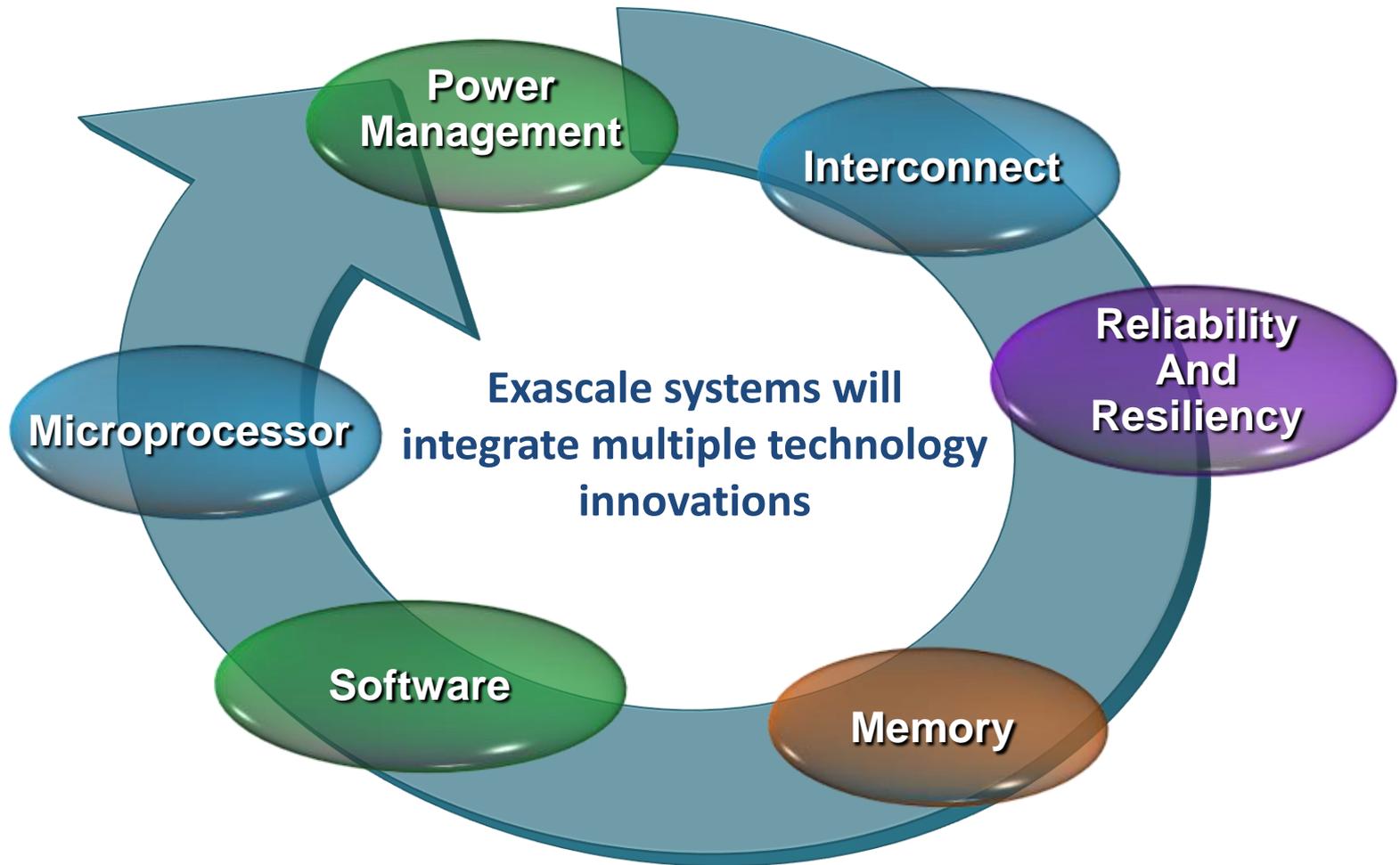
# The Path Forward

## Research Needed to Achieve Exascale Performance

- Extreme voltage scaling to reduce core power
- More parallelism 10x – 100x to achieve speed
- Re-architecting DRAM to reduce memory power
- New interconnect lower power and distance
- NVM to reduce disk power and accesses
- Resilient design to manage unreliable transistors
- New programming tools for extreme parallelism
- Applications built for extreme parallelism

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# Co-design is Essential



Co-design key to SCC, MIC, and our SoC products

Software and Services Group

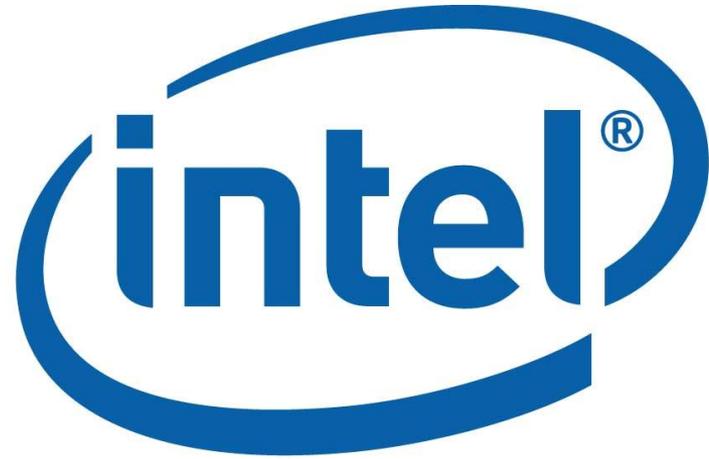
# Working with the Open Source Community

- Intel contributes substantially to OSS
  - Linux kernel, GNU tool chain, ...
- Intel's products focus on developer tools
  - Compilers, MKL, MPI, correctness and performance tools, ...
- The OS, libraries, and runtime environment, programming models, other languages and tools, execution frameworks, resource managers, parallel file systems, &etc are all driven by or provided by vendors and the community
- Getting to exascale will provide substantial challenges
  - New approaches will likely be required

# Backup

# OSS Contributors

- Intel employs a large number of OSS maintainers and contributors
  - Kristen Carlson Accardi
  - H Peter Anvin
  - Len Brown
  - Alan Cox
  - Dirk Hohndel
  - Andi Kleen
  - Auke Kok
  - HJ Lu
  - Tony Luck
  - Venki Pallipadi
  - Inaki Perez-Gonzalez
  - Arjan van de Ven
  - Matthew Wilcox
  - David Woodhouse
  - and many more...
- In Linux 2.6 kernels, as of Oct 13, 2010:
  - 11,048 patch sets by 258 Intel authors



**Software**